

The listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

1. (Currently Amended) A semiconductor device comprising:

an integrated circuit using a thin film transistor;

an antenna;

a first sealing film;

a second sealing film; [[and]]

a substrate[[.]] ; and

an adhesive.

wherein the integrated circuit and the antenna are electrically connected to each other,

the integrated circuit is sandwiched between the first sealing film and the second sealing film,

the first sealing film is sandwiched between the substrate and the integrated circuit,

the first sealing film is attached to the substrate with the adhesive.

the first sealing film includes a plurality of first insulating films and one or a plurality of second insulating films sandwiched between the plurality of first insulating films,

the second sealing film includes a plurality of third insulating films and one or a plurality of fourth insulating films sandwiched between the plurality of third insulating films,

the one or the plurality of second insulating films has lower stress than the plurality of first insulating films,

the one or the plurality of fourth insulating films has lower stress than the plurality of third insulating films, [[and]]

the plurality of first insulating films and the plurality of third insulating films are inorganic insulating films, and

a stack of the adhesive, the first sealing film, the integrated circuit, and the antenna is covered with the second sealing film.

2. (Currently Amended) A semiconductor device comprising:

an integrated circuit using a thin film transistor;

an antenna;

a first sealing film;

a second sealing film;

a substrate; [[and]]

a first adhesive;

a second adhesive; and

a cover member,

wherein the integrated circuit and the antenna are electrically connected to each other,

the integrated circuit is sandwiched between the first sealing film and the second sealing film,

the first sealing film and the second sealing film are sandwiched between the substrate and the cover member,

the first sealing film is attached to the substrate with the first adhesive.

the first sealing film includes a plurality of first insulating films and one or a plurality of second insulating films sandwiched between the plurality of first insulating films,

the second sealing film includes a plurality of third insulating films and one or a plurality of fourth insulating films sandwiched between the plurality of third insulating films,

the one or the plurality of second insulating films has lower stress than the plurality of first insulating films,

the one or the plurality of fourth insulating films has lower stress than the plurality of third insulating films, [[and]]

the plurality of first insulating films and the plurality of third insulating films are inorganic insulating films; and

the second sealing film is attached to the substrate provided with the first adhesive, the first sealing film, and the integrated circuit with the second adhesive.

3. (Currently Amended) A semiconductor device comprising:

an integrated circuit using a thin film transistor;

an antenna;

a first sealing film;

a second sealing film;

a substrate; [[and]]

a first adhesive;

a second adhesive; and

a cover member,

wherein the integrated circuit and the antenna are electrically connected to each other,

the integrated circuit and the antenna are sandwiched between the first sealing film and the second sealing film,

the first sealing film and the second sealing film are sandwiched between the substrate and the cover member,

the first sealing film is attached to the substrate with the first adhesive.

the first sealing film includes a plurality of first insulating films and one or a plurality of second insulating films sandwiched between the plurality of first insulating films,

the second sealing film includes a plurality of third insulating films and one or a plurality of fourth insulating films sandwiched between the plurality of third insulating films,

the one or the plurality of second insulating films has lower stress than the plurality of first insulating films,

the one or the plurality of fourth insulating films has lower stress than the plurality of third insulating films, [[and]]

the plurality of first insulating films and the plurality of third insulating films are inorganic insulating films, and

the second sealing film is attached to the substrate provided with the first adhesive, the first sealing film, the integrated circuit, and the antenna with the second adhesive.

4. (Original) The semiconductor device according to claim 2 or 3, wherein the cover member has flexibility.

5. (Currently Amended) The semiconductor device according to any one of claim 1 through claim 3, wherein the antenna and a gate electrode of the thin film transistor are formed by patterning using a conductive film.

6. (Currently Amended) The semiconductor device according to any one of claim 1 through claim 3, wherein the antenna and a wiring connected to the thin film transistor are formed by patterning using a conductive film.

7. (Currently Amended) A semiconductor device comprising:

an integrated circuit using a thin film transistor;

an antenna;

a first sealing film;

a second sealing film;

a substrate; [[and]]

a first adhesive;

a second adhesive; and

a cover member,

wherein the integrated circuit is sandwiched between the first sealing film and the second sealing film,

the first sealing film and the second sealing film are sandwiched between the substrate and the cover member,

the first sealing film is attached to the substrate with the first adhesive;

the cover member is sandwiched between the antenna and the second sealing film,

the integrated circuit and the antenna are electrically connected to each other via a contact hole formed in the cover member and the second sealing film with the second adhesive.

the first sealing film includes a plurality of first insulating films and one or a plurality of second insulating films sandwiched between the plurality of first insulating films,

the second sealing film includes a plurality of third insulating films and one or a plurality of fourth insulating films sandwiched between the plurality of third insulating films,

the one or the plurality of second insulating films has lower stress than the plurality of first insulating films,

the one or the plurality of fourth insulating films has lower stress than the plurality of third insulating films, [[and]]

the plurality of first insulating films and the plurality of third insulating films are inorganic insulating films, and

the second sealing film is attached to the substrate provided with the first adhesive, the first sealing film, and the integrated circuit with the second adhesive.

8. (Original) The semiconductor device according to claim 7, wherein the cover member has flexibility.

9. (Currently Amended) A semiconductor device comprising:

an integrated circuit using a thin film transistor;

a first sealing film;

a second sealing film; [[and]]

an adhesive; and

a substrate,

wherein the integrated circuit is sandwiched between the first sealing film and the second sealing film,

the first sealing film is sandwiched between the substrate and the integrated circuit,

the first sealing film is attached to the substrate with the adhesive,

the integrated circuit includes a connection terminal,

the integrated circuit further includes a rectification circuit for generating a supply voltage from an alternating-current signal that is input in the connection terminal by an antenna; a demodulation circuit for generating a first signal by demodulating the alternating-current signal; a microprocessor for performing arithmetic processing in accordance with the first signal to generate a second signal; a modulation circuit for modulating the second signal; and a switch for modulating load applied to the antenna in accordance with the modulated second signal,

the first sealing film includes a plurality of first insulating films and one or a plurality of second insulating films sandwiched between the plurality of first insulating films,

the second sealing film includes a plurality of third insulating films and one or a plurality of fourth insulating films sandwiched between the plurality of third insulating films,

the one or the plurality of second insulating films has lower stress than the plurality of first insulating films,

the one or the plurality of fourth insulating films has lower stress than the plurality of third insulating films, and

the plurality of first insulating films and the plurality of third insulating films are inorganic insulating films.

10. (Currently Amended) The semiconductor device according to any one of claims ~~4-3 and 7-9~~ 1-3, 7 and 9, wherein the substrate has flexibility.

11. (Currently Amended) The semiconductor device according to any one of claims ~~4-3 and 7-9~~ 1-3, 7 and 9, wherein the plurality of first insulating films or the plurality of third insulating films includes silicon nitride, silicon nitride oxide, aluminum oxide, aluminum nitride, aluminum nitride oxide or aluminum silicon nitride oxide.

12. (Currently Amended) The semiconductor device according to any one of claims ~~4-3 and 7-9~~ 1-3, 7 and 9, wherein the one or the plurality of second insulating films or the one or the plurality of fourth insulating films includes polyimide, acrylic, polyamide, polyimide amide, benzocyclobutene or epoxy resin.